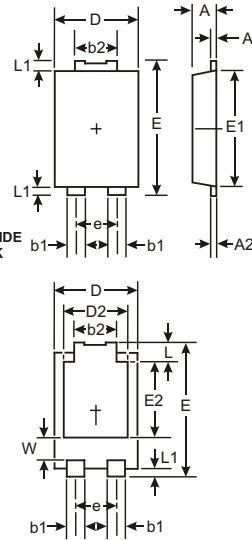
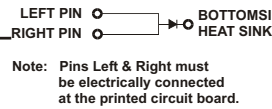


Features

- Guard Ring Die Construction for Transient Protection
- Low Forward Voltage Drop
- Very Low Leakage Current
- Highly Stable Oxide Passivated Junction
- High Forward Surge Current Capability
- Lead Free Finish, RoHS Compliant (Note 1)**
- "Green" Molding Compound (No Br, Sb)**

Mechanical Data

- Case: PowerDI 5
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture sensitivity: Level 1 per J-STD-020C
- Terminals: Finish – Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208 **(E3)**
- Polarity: See Diagram
- Marking: See Page 3
- Weight: 0.096 grams (approx.)



PowerDI 5		
Dim	Min	Max
A	1.05	1.15
A2	0.33	0.43
b1	0.80	0.99
b2	1.70	1.88
D	3.90	4.05
D2	3.05 NOM	
E	6.40	6.60
e	1.84 NOM	
E1	5.30	5.45
E2	3.55 NOM	
L	0.75	0.95
L1	0.50	0.65
W	1.20	1.50
All Dimensions in mm		

Maximum Ratings @ T_A = 25 C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	200	V
RMS Reverse Voltage	V _{R(RMS)}	141	V
Average Rectified Output Current (See also figure 5)	I _O	3	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave Superimposed on Rated Load	I _{FSM}	180	A

Thermal Characteristics

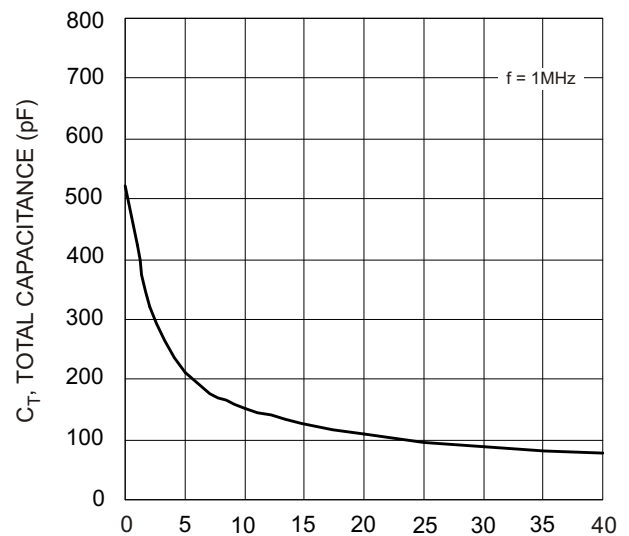
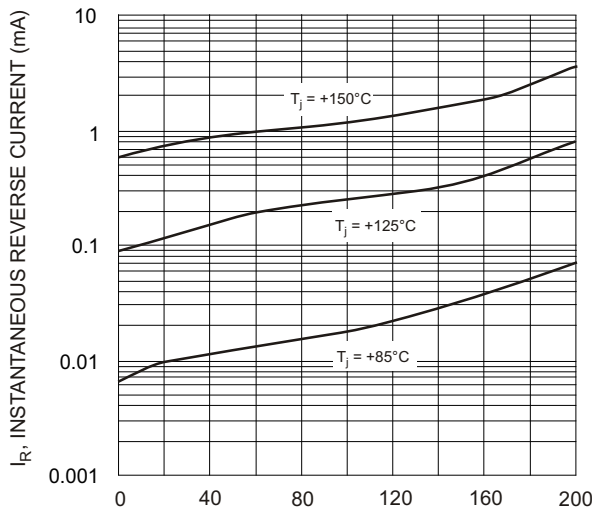
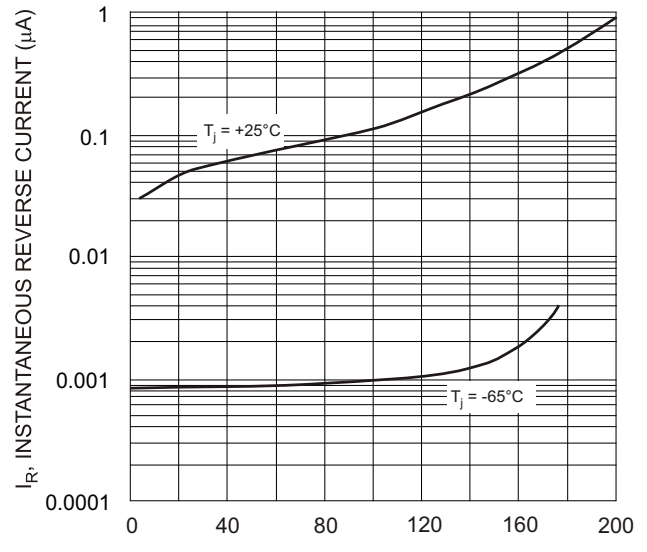
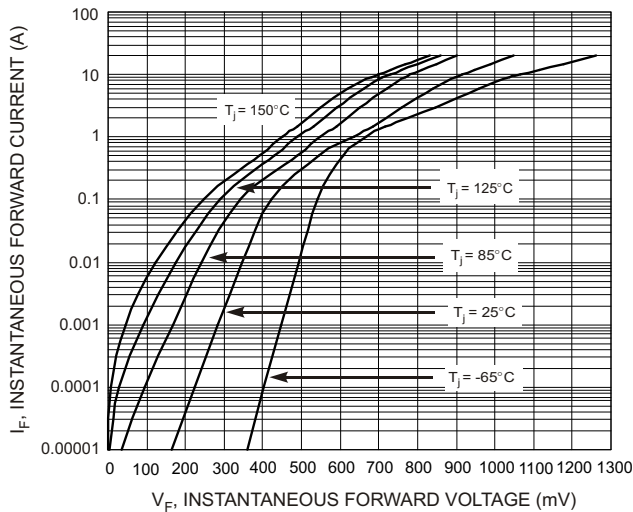
Characteristic	Symbol	Typ	Max	Unit
Thermal Resistance Junction to Soldering Point	R _{JS}		2.0	C/W
Thermal Resistance Junction to Ambient Air (Note 2) T _A = 25°C	R _{JA}	75		C/W
Thermal Resistance Junction to Ambient Air (Note 3) T _A = 25°C	R _{JA}	60		C/W
Thermal Resistance Junction to Ambient Air (Note 4) T _A = 25°C	R _{JA}	45		C/W
Operating Temperature Range	T _J	-65 to +150		°C
Storage Temperature Range	T _{STG}	-65 to +175		°C

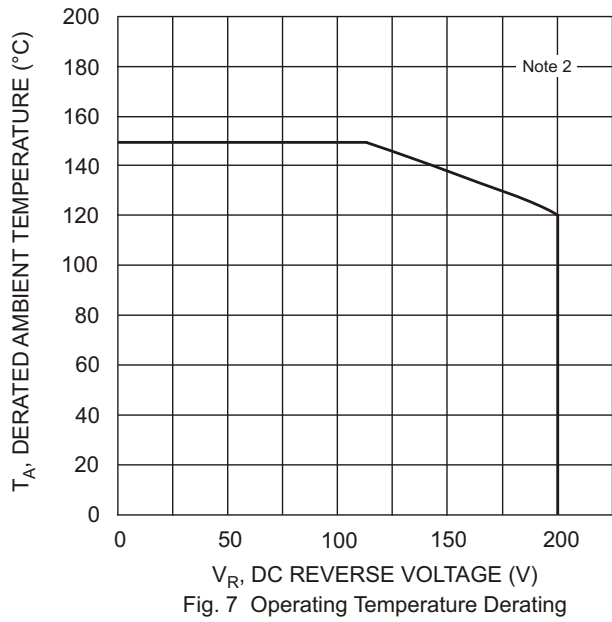
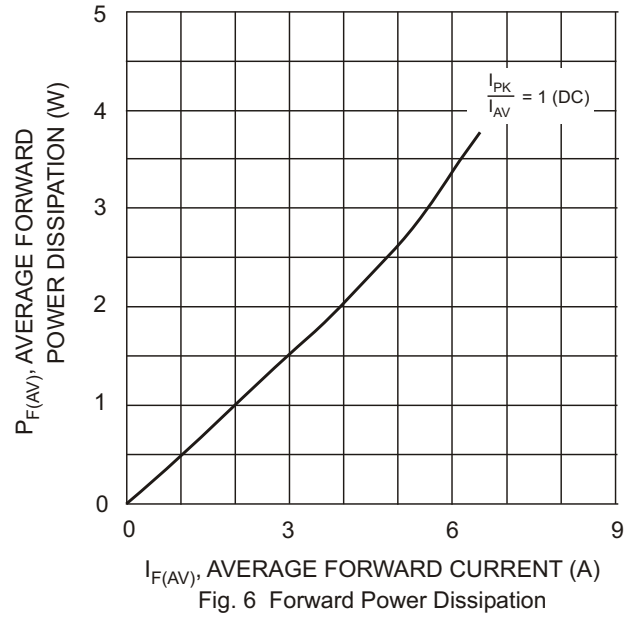
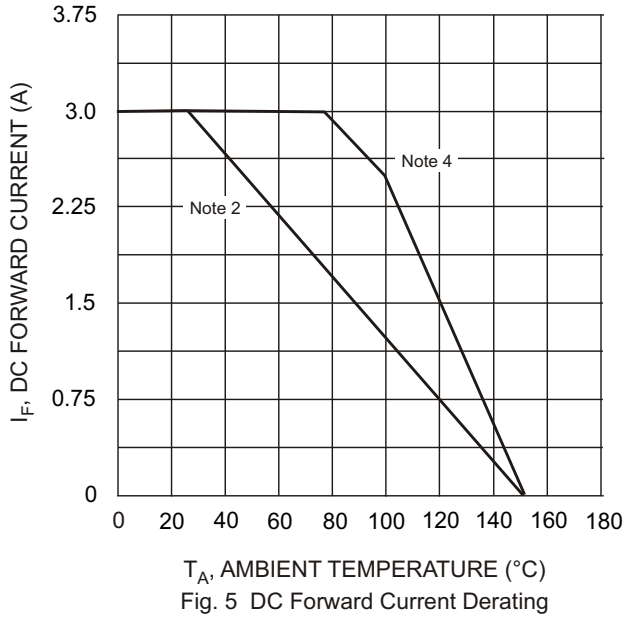
- Notes:
- RoHS revision 13.2.2003. High Temperature Solder Exemption Applied, see *EU Directive Annex Note 7*.
 - FR-4 PCB, 2 oz. Copper, minimum recommended pad layout per <http://www.diodes.com/datasheets/ap02001.pdf>.
 - Polymide PCB, 2 oz. Copper, minimum recommended pad layout per <http://www.diodes.com/datasheets/ap02001.pdf>.
 - Polymide PCB, 2 oz. Copper. Cathode pad dimensions 9.4mm x 7.2mm. Anode pad dimensions 2.7mm x 1.6mm.

Electrical Characteristics @ $T_A = 25\text{ C}$ unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 5)	$V_{(BR)R}$	200			V	$I_R = 10\text{ A}$
Forward Voltage	V_F		0.75 0.59 0.82 0.66	0.78 0.64 0.88 0.71	V	$I_F = 3\text{ A}, T_S = 25\text{ C}$ $I_F = 3\text{ A}, T_S = 125\text{ C}$ $I_F = 6\text{ A}, T_S = 25\text{ C}$ $I_F = 6\text{ A}, T_S = 125\text{ C}$
Reverse Leakage Current (Note 5)	I_R		1 0.8	10 4.5	A mA	$T_S = 25\text{ C}, V_R = 200\text{ V}$ $T_S = 125\text{ C}, V_R = 200\text{ V}$

Notes: 5. Short duration test pulse used to minimize self-heating effect.



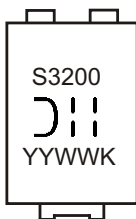


Ordering Information (Note 6)

Device	Packaging	Shipping
PDS3200-13	PowerDI 5	5000/Tape & Reel

- Notes:
- FR-4 PCB, 2 oz. Copper, minimum recommended pad layout per <http://www.diodes.com/datasheets/ap02001.pdf>.
 - Polymide PCB, 2 oz. Copper, minimum recommended pad layout per <http://www.diodes.com/datasheets/ap02001.pdf>.
 - Polymide PCB, 2 oz. Copper. Cathode pad dimensions 9.4mm x 7.2mm. Anode pad dimensions 2.7mm x 1.6mm.
 - Short duration test pulse used to minimize self-heating effect.
 - For Packaging Details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

Marking Information



S3200 = Product type marking code
 Jii = Manufacturers' code marking
 YYWW = Date code marking
 YY = Last digit of year ex: 04 for 2004
 WW = Week code 01 to 52
 K = Factory Designator

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